



Product Information

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MS-900 Silicone Sealant

Description:

MS-900 sealant is a one-part, moisture-curing RTV silicone sealant/adhesive that is non-slump and cures to form a tough, permanent rubber seal or bond. The non-corrosive curing system of the product makes it ideally suited for protecting, sealing and insulating corrosion-sensitive electronic and electrical materials such as copper, brass, silver, etc.

Advantages:

- Good dielectric properties
- High surface resistivity
- Resists electrical tracking
- Repels water to protect electrical properties
- Excellent weatherability
- Excellent chemical resistance
- Excellent color retention
- Ozone and UV resistant
- Meets requirements of MIL-46106 Type I

Applications:

- Lead-wire
- Conduit thermal box
- Electrical connections
- Coaxial cable connectors
- Conductor entry holes
- Cover plates
- Component mounting
- Conduit ends and slices
- Printed circuit boards

Cured Properties:

Shore hardness D (ASTM D2240)	30 ± 2
Tensile @ break (ASTM D412)	250 ± 25 psi
Elongation @ 100% break (ASTM D412)	400 ± 25%
Modulus @ 100% elongation (ASTM D412)	90 ± 10 psi
Tear strength (ASTM 64 [Die B])	30 ± 10 ppi
Adhesion strength (PEEL) TT-S-001543, 3.5.9)	
Glass	10 ± 2 ppi
Aluminum (Primed)	8 ± 2 ppi
Mortar (Primed)	12 ± 2 ppi

Sag or Slump (TT-S-001543, 3.5.6)	Nil
Shrinkage (wt. loss, TT-S-001543, 5.5)	< 5%
Extrusion Rate (1/8" orifice @ 50 psi)	130 ± 5 gm/min
Service Temperature	-18°C to 50°C/0° to 120°F

Electrical Properties:

Dissipation Factor (ASTM D150)	50 Hz-0.0009 1 kHz-0.0004 1 MHz-0.0002
Dielectric Constant (ASTM D150)	50 Hz-2.7 1 kHz-2.7 1 MHz-2.7
Volume resistivity, ohm.cm (ASTM D257)	2 x 10 ¹⁴
Surface resistivity, ohm.cm (ASTM D257)	3 x 10 ¹⁵
Dielectric strength, Kv/mm (ASTM D149)	18

Directions:

All substrates must be clean, dry and free from surface contamination. Do not use with oil-based solvent. Allow surface to dry thoroughly. The cure mechanism begins as soon as the sealant comes in contact with air. At conditions of 77°F/25°C and 50% humidity, the sealant will "skin cover" in 15 minutes and fully cure within 48 hours (1/8 bead). Higher humidity accelerates cure. Tooling should be done before skinning takes place. Priming of surfaces to be sealed or bonded is normally not required for applications to most substrates.

Safety Data Sheet (SDS) is available upon request.

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